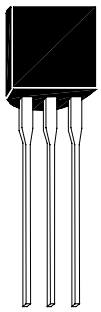
H2N5401

PNP EPITAXIAL PLANAR TRANSISTOR



TO-92

Description

The H2N5401 is designed for general purpose applications requiring high breakdown voltages.

Features

- Complements to NPN Type H2N5551
- High Collector-Emitter Breakdown Voltage (VCEO=150V (@IC=1mA))

Absolute Maximum Ratings

- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)
  VCBO Collector to Base Voltage ..... -160 V
  VCEO Collector to Emitter Voltage ..... -150 V
  VEBO Emitter to Base Voltage ..... -5 V
  IC Collector Current ..... -600 mA

Characteristics (Ta=25°C)

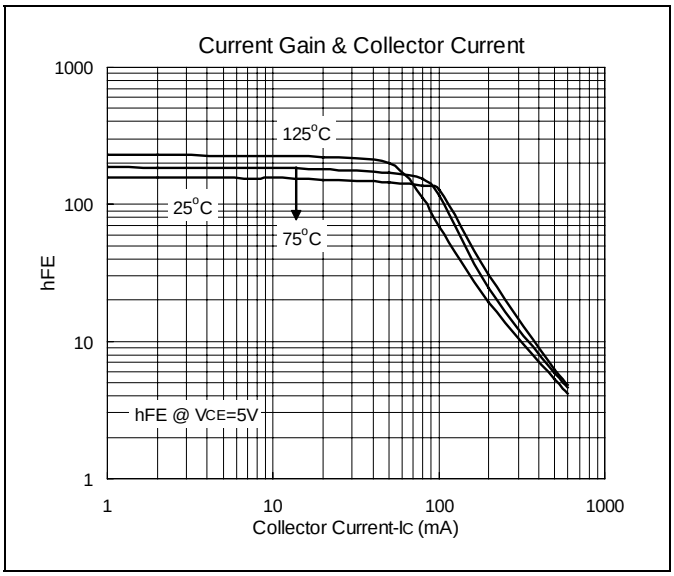
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-160	-	-	V	IC=-100uA, IE=0
BVCEO	-150	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-50	nA	VCB=-120V, IE=0
IEBO	-	-	-50	nA	VEB=-3V. IC=0
*VCE(sat)1	-	-	-0.2	V	IC=-10mA, IB=-1mA
*VCE(sat)2	-	-	-0.5	V	IC=-50mA, IB=-5mA
*VBE(sat)1	-	-	-1	V	IC=-10mA, IB=-1mA
*VBE(sat)2	-	-	-1	V	IC=-50mA, IB=-5mA
*hFE1	50	-	-		VCE=-5V, IC=-1mA
*hFE2	80	160	400		VCE=-5V, IC=-10mA
*hFE3	50	-	-		VCE=-5V, IC=-50mA
fT	100	-	300	MHz	VCE=-10V, IC=-10mA, f=100MHz
Cob	-	-	6	pF	VCB=-10V, f=1MHz, IE=0

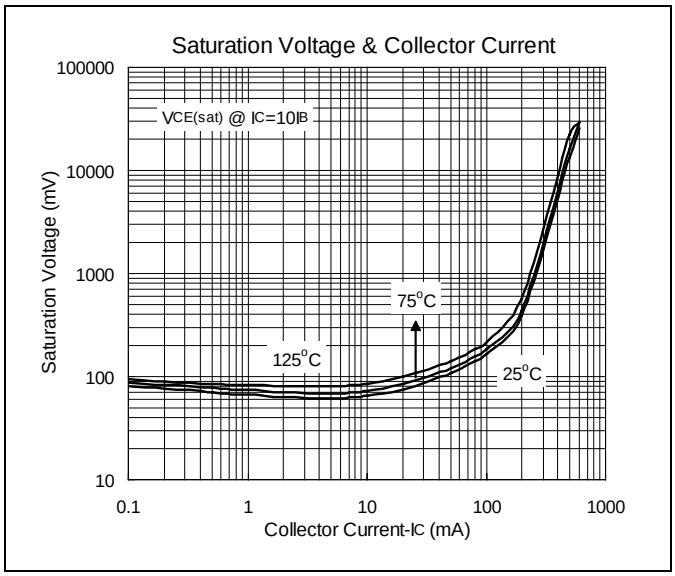
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

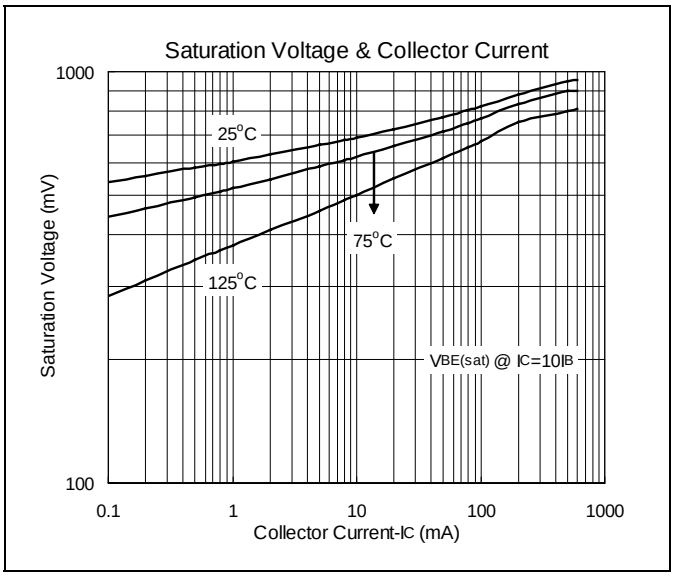
Classification of hFE2

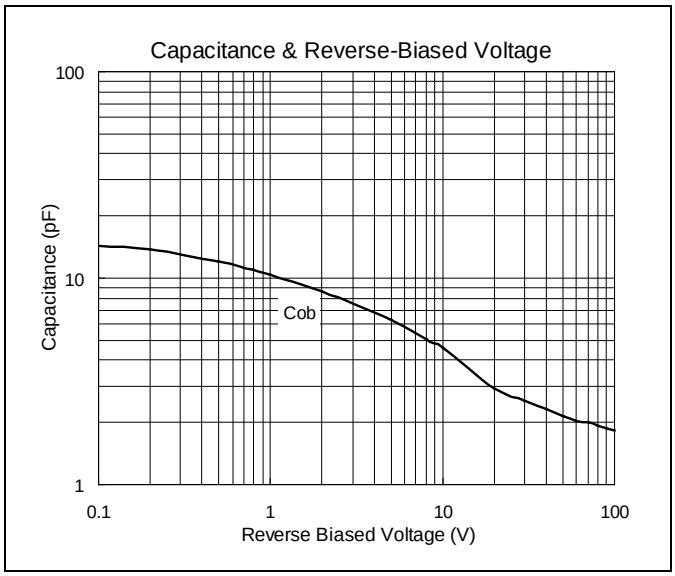
Rank	A	N	C
Range	80-200	100-240	160-400

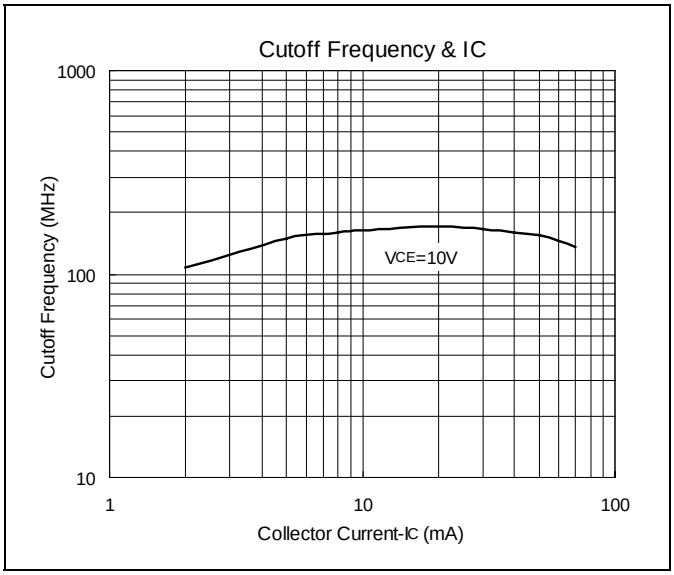
Characteristics Curve

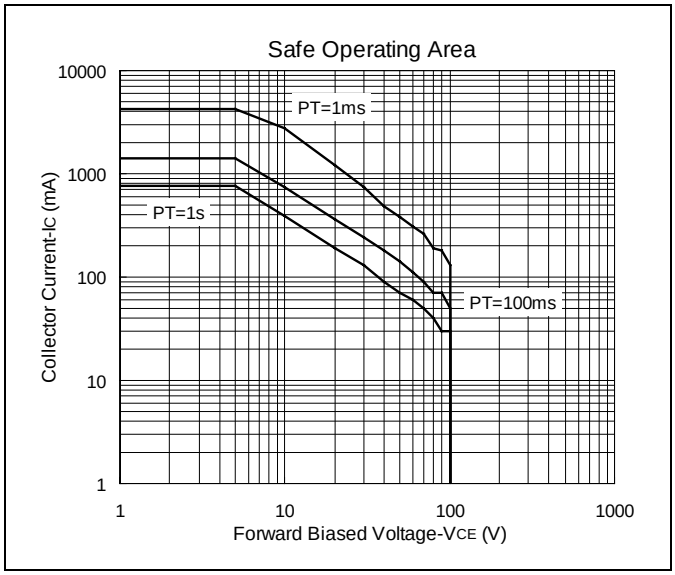


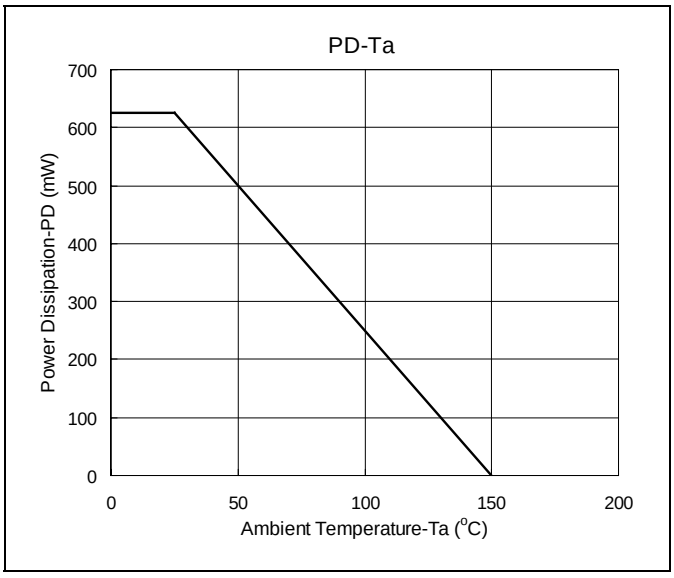




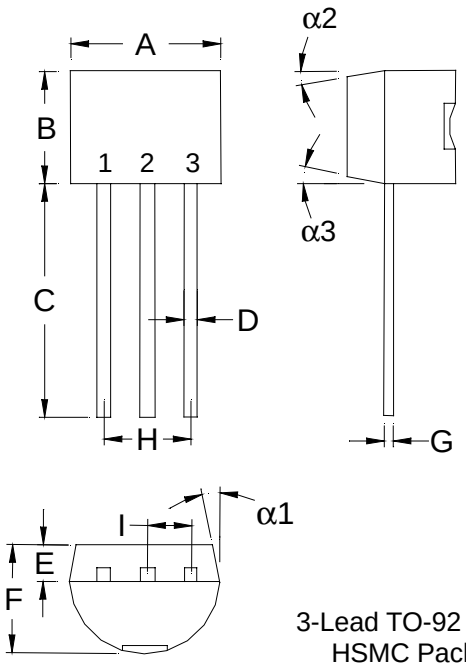






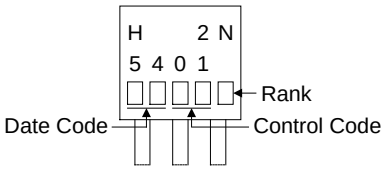

PD-Ta
Power Dissipation-PD (mW)
700
600
500
400
300
200
100
0
0
50
100
150
200
Ambient Temperature-Ta (°C)

TO-92 Dimension



3-Lead TO-92 Plastic Package
HSMC Package Code: A

Marking:



Style: Pin 1.Emitter 2.Base 3.Collector

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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